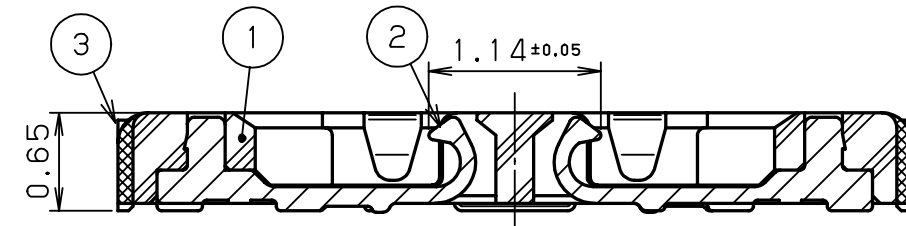
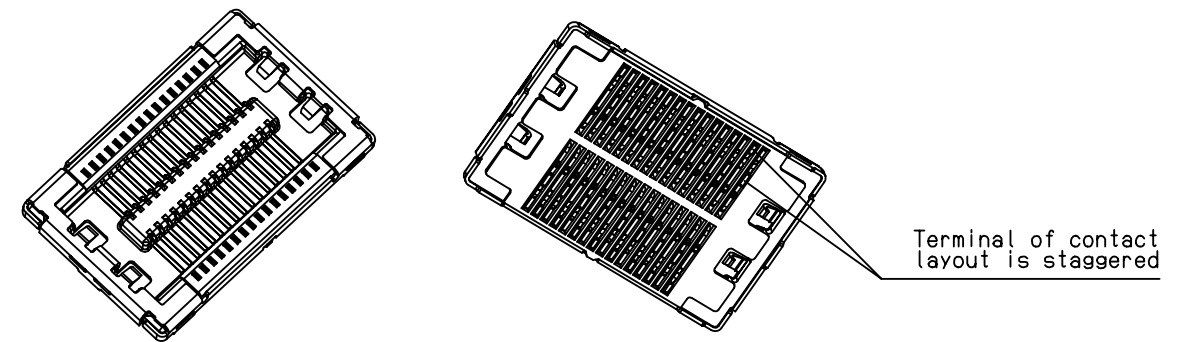
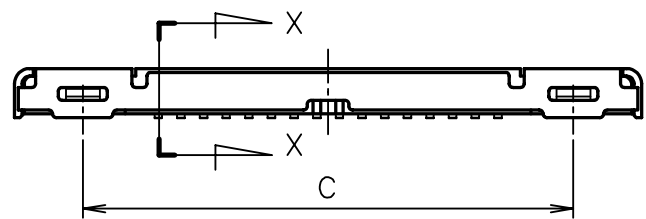


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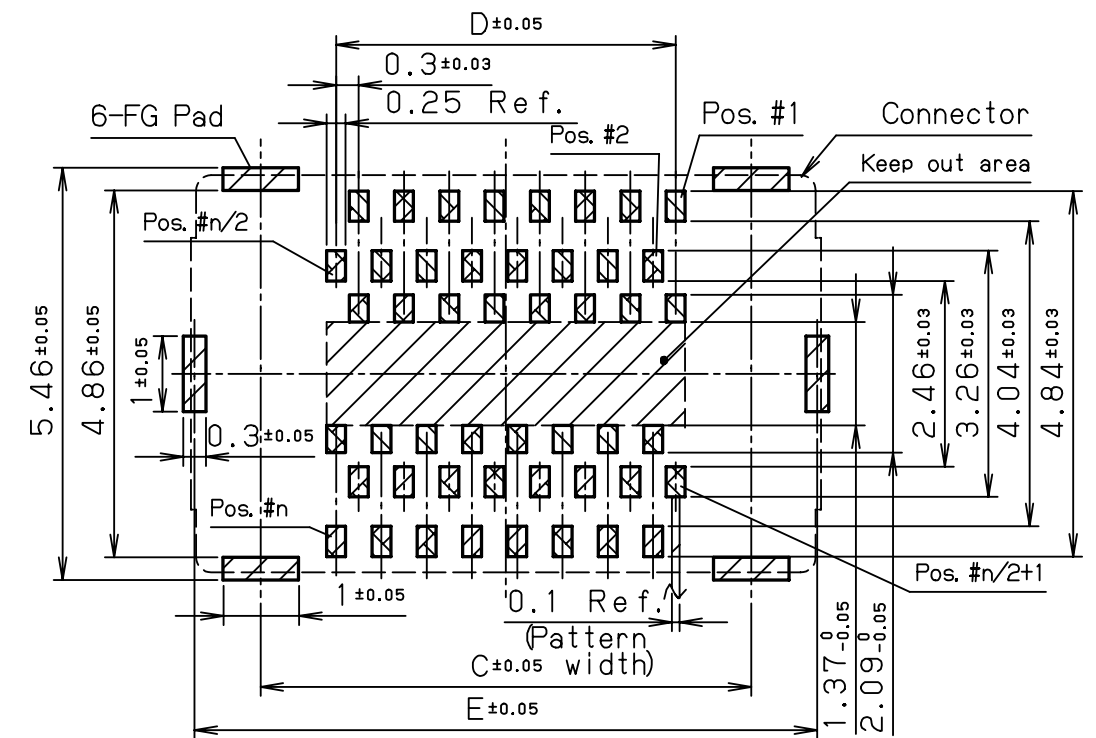


X-X Section



Note

1. Contact Plating
Contact area: Gold $0.1\mu\text{m}$
Terminal area: Gold flash
Underplating: Nickel
(Under the use of N2 -reflow excluded.)
2. Mating Connector
P/N: LPZ- () SMY+
3. Contact and Hold down co-planarity is 0.08mm MAX.



Recommended P.C.B. layout

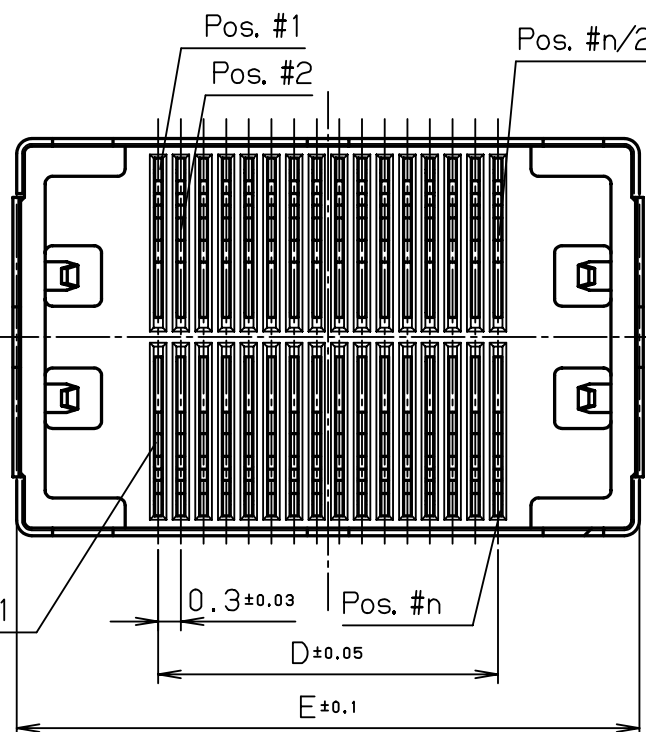


Table-1

Part No.	n	A	B	C
LPZ-E24SFY+	24	7.15	3.94	5.3
LPZ-E32SFY+	32	8.35	5.14	6.5
LPZ-E40SFY+	40	9.55	6.34	7.7
LPZ-E60SFY+	60	12.55	9.34	10.7

D	E
3.3	7.05
4.5	8.25
5.7	9.45
8.7	12.45

改版 LTR.	年月日 DATE	変更者 BY	変更内容 REV. DESCRIPT	番号 No.	部品名称 PART NAME	材質 MATERIAL	個数 QTY	処 理 FINISH	備 考 NOTE
				3	Shell	Copper alloy	1	Tin	
				2	Contact	Copper alloy	n	See Note #1	
				1	Insulator	LCP (GF)	1		UL94V-0 Black
年月日 DATE	尺度 SCALE	単位 UNIT	3角法	本多通信工業株式会社 HONDA TSUSHIN KOGYO CO., LTD.					
Jly.21 (2006)	10/1	mm (INCH)	3RD. A. P	製 図 DR.	設 計 DE.	検 査 CHK.	検 査 CHK.	承 認 APP.	名 称 NAME
K. KUWANA	K. KUWANA	K. TAKAHASHI		K. KASAI	製 番 PART NO.	LPZ-E () SFY+		備 考 NOTE	考
0.3mm pitch stacking receptacle connector SMT termination and shield type. (Stack height is 0.7mm)									REV.